

WHAT IS CLAIMED IS:

1. A light emitting device comprising:
a light emitting element at a front surface of a substrate;
a color filter at a back surface of the substrate.
- 5 2. A light emitting device comprising:
at least a pixel including a light emitting element at front surface of a
substrate;
a transparent substrate comprising at least a colored layer,
wherein the transparent substrate is located at a back surface of the
10 substrate having a resin film interposed therebetween.
3. A device according to claim 2,
wherein the colored layer is formed corresponding to a position of the
pixel.
- 15 4. A device according to claim 2,
wherein the transparent substrate comprises an antireflection film or a
polarization plate.
5. A device according to claim 2,
wherein the transparent substrate comprises a polymeric material.
- 20 6. A device according to claim 2,
wherein the transparent substrate comprises a polymeric material,

wherein a front surface and a back surface of the transparent substrate are covered by a carbon film or a silicon nitride film.

7. A device according to claim 1,
wherein the substrate has a thickness in a range of 300 μm or less.

5 8. A device according to claim 1,
wherein the light emitting element is electrically connected to a semiconductor element.

9. A method of manufacturing a light emitting device, said method comprising the steps of:

forming a light emitting element at a front surface of a substrate;
bonding a color filter at a back surface of the substrate.

10. A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being
15 electrically connected to the semiconductor element at a front surface of a substrate;
bonding a color filter at a back surface of the substrate.

11. A method of manufacturing a light emitting device, said method comprising the steps of:

20 forming a light emitting element at a front surface of a substrate;
bonding a transparent substrate comprising at least a colored layer at a

back surface of the substrate.

12. A method of manufacturing a light emitting device, said method comprising the steps of:

forming a semiconductor element and a light emitting element being electrically connected to the semiconductor element at a front surface of a substrate;

bonding a transparent substrate comprising at least a colored layer at a back surface of the substrate.

13. A method according to claim 11, further comprising the step of:

bonding an antireflection film or a polarization plate to the transparent substrate.

14. A method according to claim 11,

wherein the transparent substrate comprises a polymeric material.

15. A method according to claim 9, further comprising the step of:

polishing the back surface of the substrate by a chemical mechanical polishing method.

16. A method according to claim 10, further comprising the step of:

polishing the back surface of the substrate by a chemical mechanical polishing method.

17. A method according to claim 11, further comprising the step of:

polishing the back surface of the substrate by a chemical mechanical polishing method.

18. A method according to claim 12, further comprising the step of:
bonding an antireflection film or a polarization plate to the transparent
5 substrate.

19. A method according to claim 12,
wherein the transparent substrate comprises a polymeric material.

20. A method according to claim 12, further comprising the step of:
polishing the back surface of the substrate by a chemical mechanical
10 polishing method.

21. A device according to claim 2,
wherein the substrate has a thickness in a range of 300 μm or less.

22. A device according to claim 2,
wherein the light emitting element is electrically connected to a
15 semiconductor element.